

Serial No.: 10/695,018

Atty Docket No.: JCLA11476-R2

**AMENDMENT**

**In The Drawings:**

Please amend Figures 1A, 1B, 2A, and 2B according to the replacement drawings as attached herewith.

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**REMARKS****Present Status of the Application**

This is a full and timely response to the Advisory Action mailed on November 03, 2005. Furthermore, the Final Office Action mailed on August 04, 2005 has rejected claims 1-19 under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA), previously cited, in view of Vinson et al (US 6,700,794), newly cited. The Advisory Action mailed on November 03, 2005 has indicated that the Amendment After Final previously filed will not be entered because it raises new issues that would require further consideration and/or search.

The portion of which that required further consideration and/or search as asserted by the Examiner in the Advisory Action is as follows: "wherein one of said die pads is electrically connected to said power pad or said ground pad via the first conductive wire and one of said electrodes of said passive component."

Upon traversing of the outstanding Final Office Action in this response, claims 1-19 remain pending in the present application.

The Applicants have most respectfully considered the remarks set forth in this Office Action. Regarding the obviousness rejections, it is strongly believed that the cited references are deficient to adequately teach the claimed features as recited in the claims. The reasons that motivate the above position of the Applicants are discussed in detail hereafter, upon which reconsideration of the claims is most earnestly solicited.

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**Discussion of Drawings Objection**

*Figures 1B and 2B are objected to as failing to comply with 37 CFR 1.83(a) because they show inconsistent dispositional relationships between the passive component and the electrodes 132b and 232b and it is not clear whether the electrodes are at the top end of the passive element or at the sides thereof.*

In response thereto, Applicants have amended Figures 1A, 1B, 2A, and 2B to clarify the dispositional relationships between the passive component and the electrodes 132b and 232b and to clarify that the electrodes are at the top end and bottom end of the passive element. Withdrawal of the objection is respectfully requested.

**Response to 35 U.S.C. 103 rejections**

*Claims 1-19 are rejected under 35 U.S.C. 103(a) as being unpatentable over the AAPA, previously cited, in view of Vinson et al. (US-6,700,794, hereinafter "Vinson"), newly cited.*

With regard to the 103(a) rejections of claims 1, 9, 14, and 17, Applicants respectfully traverse the 103(a) rejections based upon the following:

1. Examiner has mentioned in the Office Action mailed on August 04, 2005 that "... it would be obvious to one of ordinary skill in the art at the time of invention to connect the wire of the AAPA to the pad via the pad therein, in order to reduce the length of the wire, and avoid problems such as wire bending ..." (in page 4). Vinson only discloses a chip module having improved capacitor with decreased equivalent series inductance and equivalent series resistance (col. 2, lines 12-16). The conventional chip modules have capacitors with long interconnect

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length because the restriction on the dimensional footprint (col. 1, lines 47-59). Vinson discloses the capacitors mounted on the IC die to overcome the restriction on the footprint and achieves the objective to shorten the connecting length (col. 2, lines 30-34, and col. 3, lines 57-62). "To connect the wire of the AAPA to the pad via the pad therein, for reducing the length of the wire and other objectives" is not taught or indicated by Vinson. The first criterion of the prima facie is to have some suggestion or motivation to combine reference teachings. Such the motivation to combine AAPA and Vinson is lacked for one skill in this art according to MPEP 2143.01.

2. Vinson fails to teach or indicate to connect a die pad to a power pad or to a ground pad of the carrier via the wire connecting the die pad and the electrode of the passive component, wherein the passive component is mounted on the power pad and the ground pad. Such a connection structure are not taught or indicated by Vinson and AAPA. The amended claims 1 and 9 with the added claim limitation: "wherein one of said die pads is electrically connected to said power pad or said ground pad via the first conductive wire and one of said electrodes of said passive component" shall make claims 1 and 9 patentable over the AAPA in view of Vinson.

Based upon the aforementioned arguments, independent claims 1, 9, 14, and 17 should be allowed.

Furthermore, dependent claims 2-8, 10-13, 15-16, and 18-19 should be allowed pending the allowance of claims 1, 9, 14, and 17.

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Applicants respectfully assert that these claims also are in condition for allowance. Thus, reconsideration and withdrawal of this rejection are respectively requested.

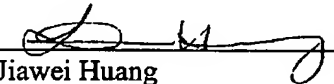
### CONCLUSION

For at least the foregoing reasons, it is believed that the presently pending claims 1-19 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

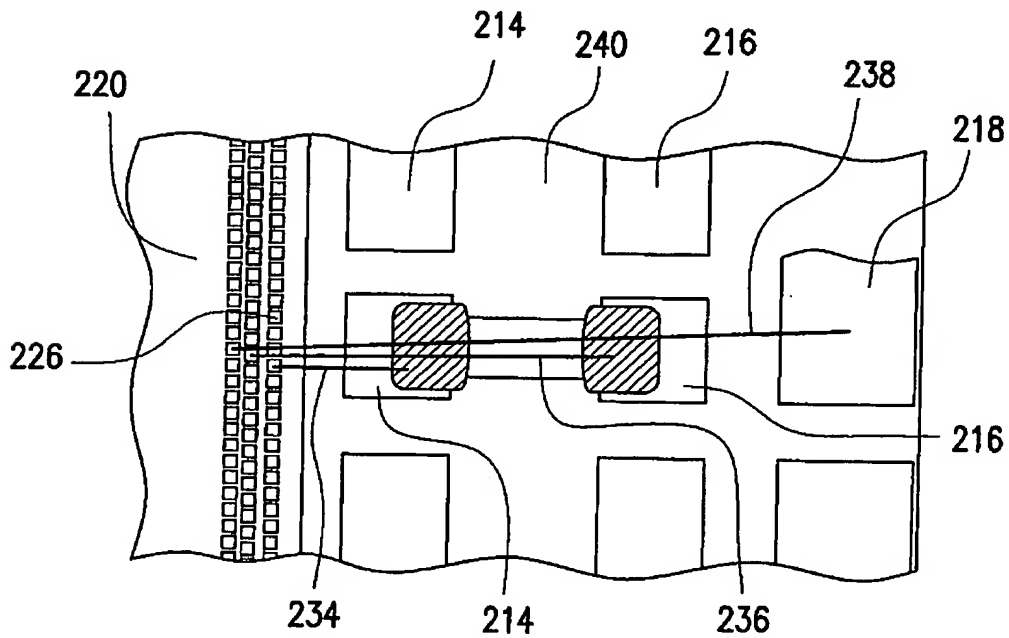
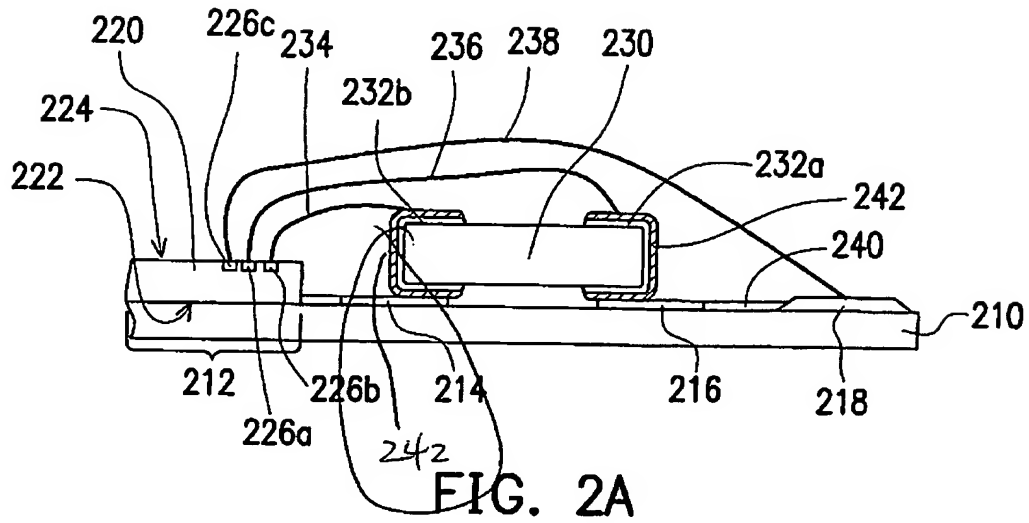
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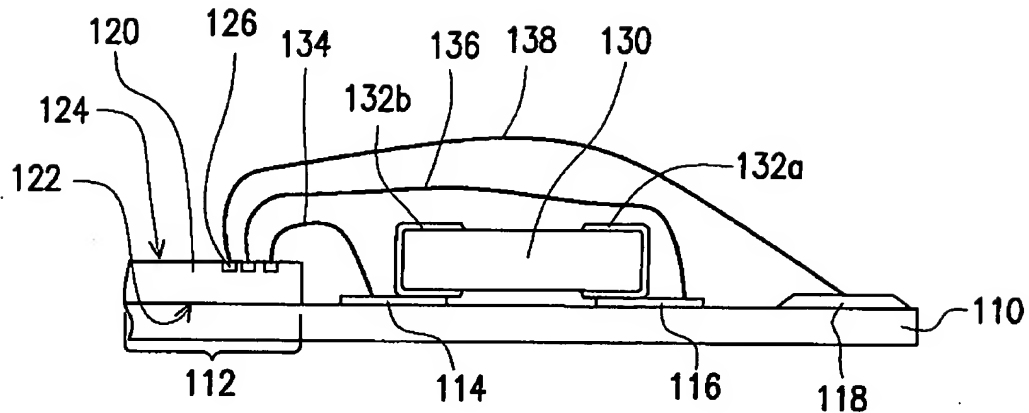


FIG. 1A (PRIOR ART)

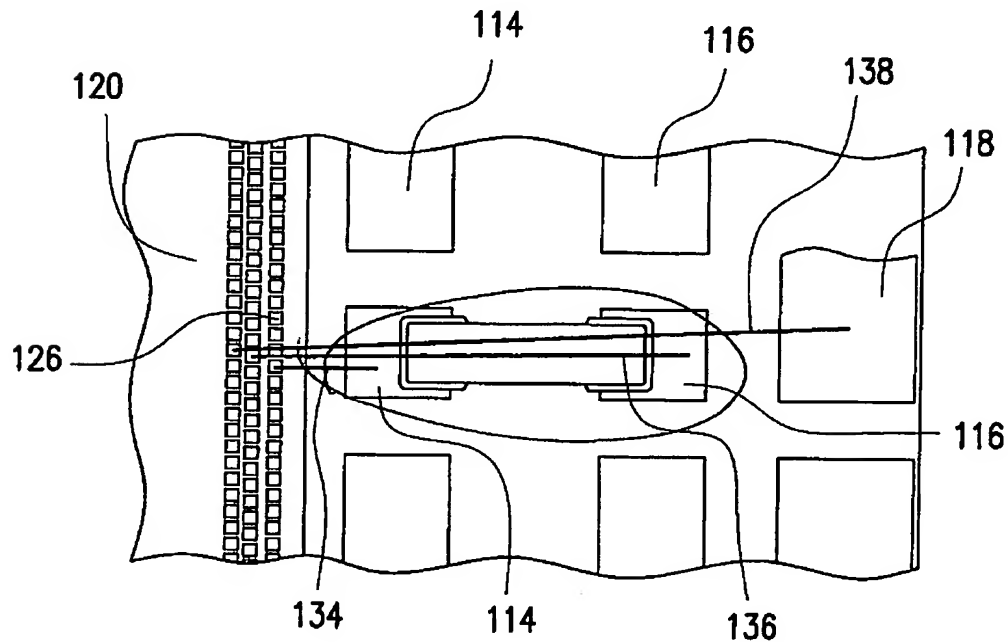


FIG. 1B (PRIOR ART)